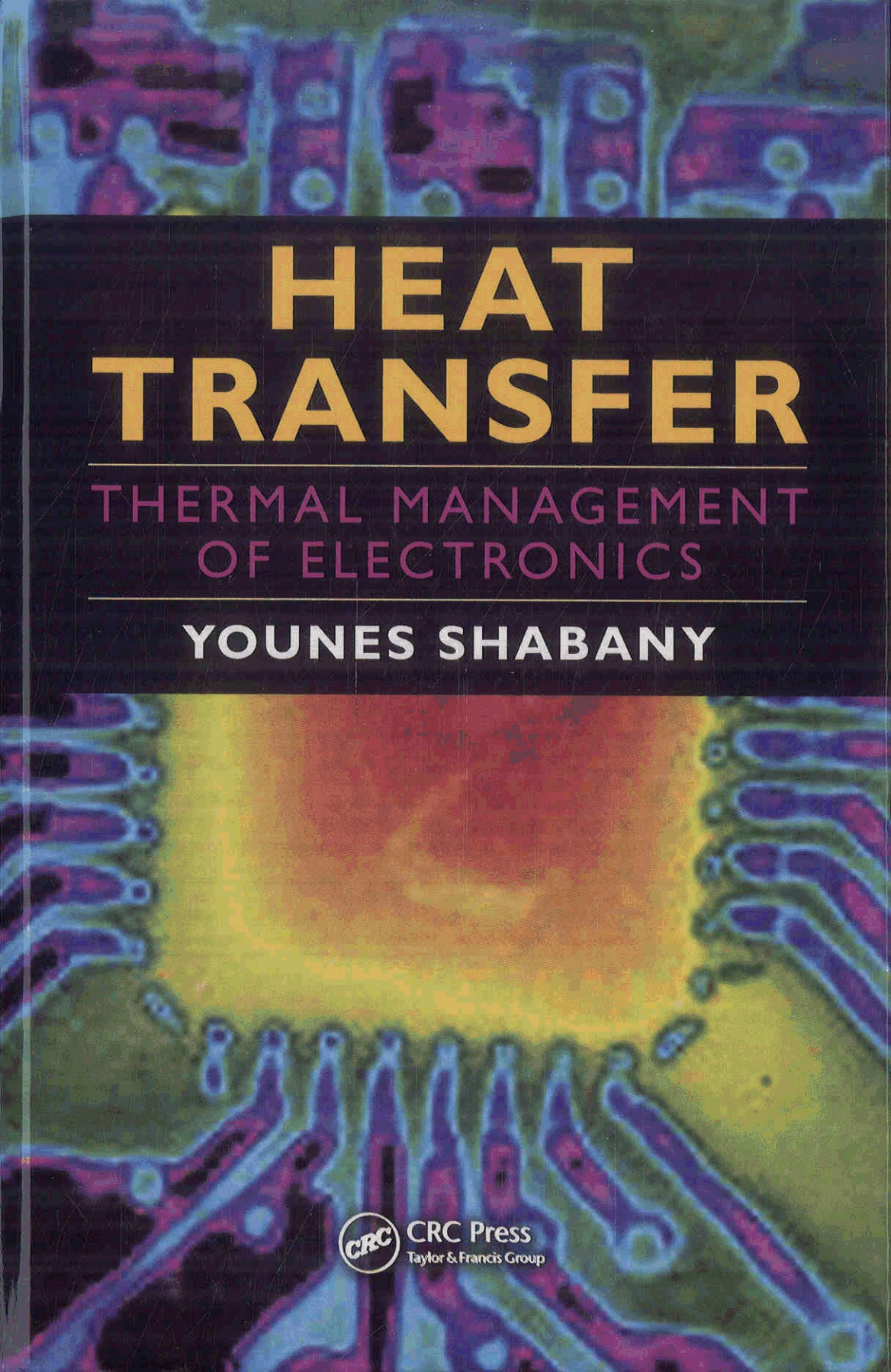


The background of the book cover is a microscopic image of a circuit board, showing intricate patterns of conductive traces and components in shades of blue, purple, and yellow.

HEAT TRANSFER

THERMAL MANAGEMENT
OF ELECTRONICS

YOUNES SHABANY



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